

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

WO 2005/062998

PCT/US2004/044097

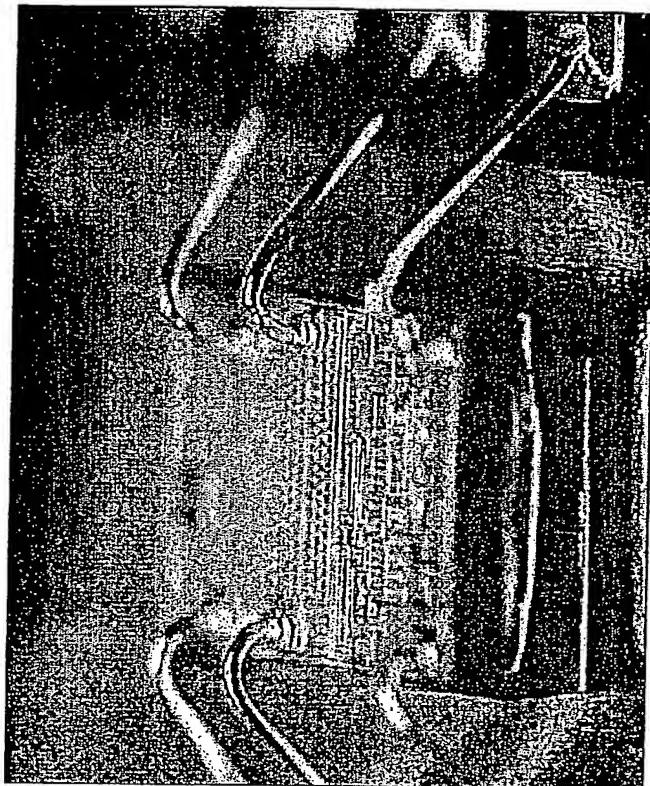


Figure 1. Example of Wire Bonding Used to Form the Electrical Connections to the Semiconductor Die

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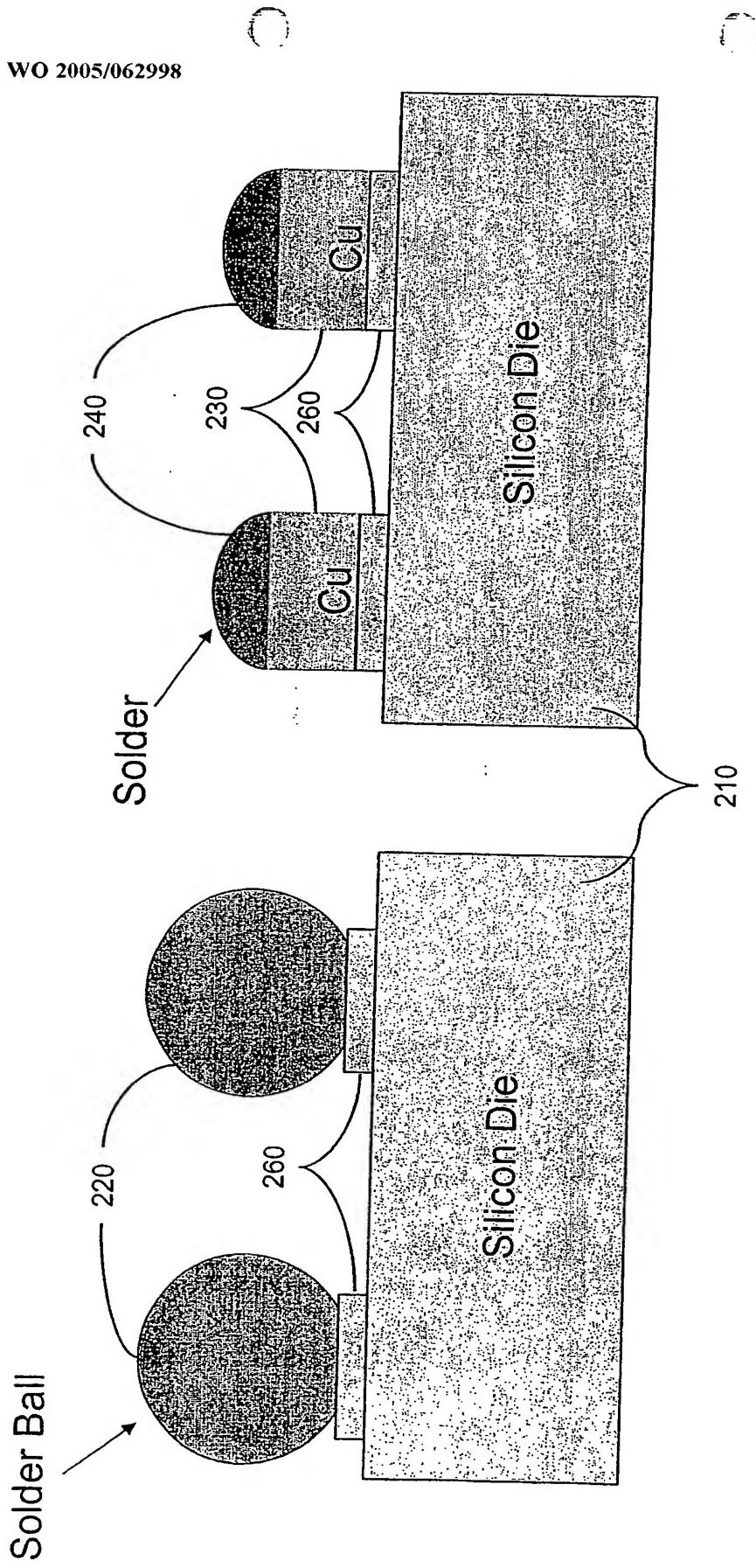
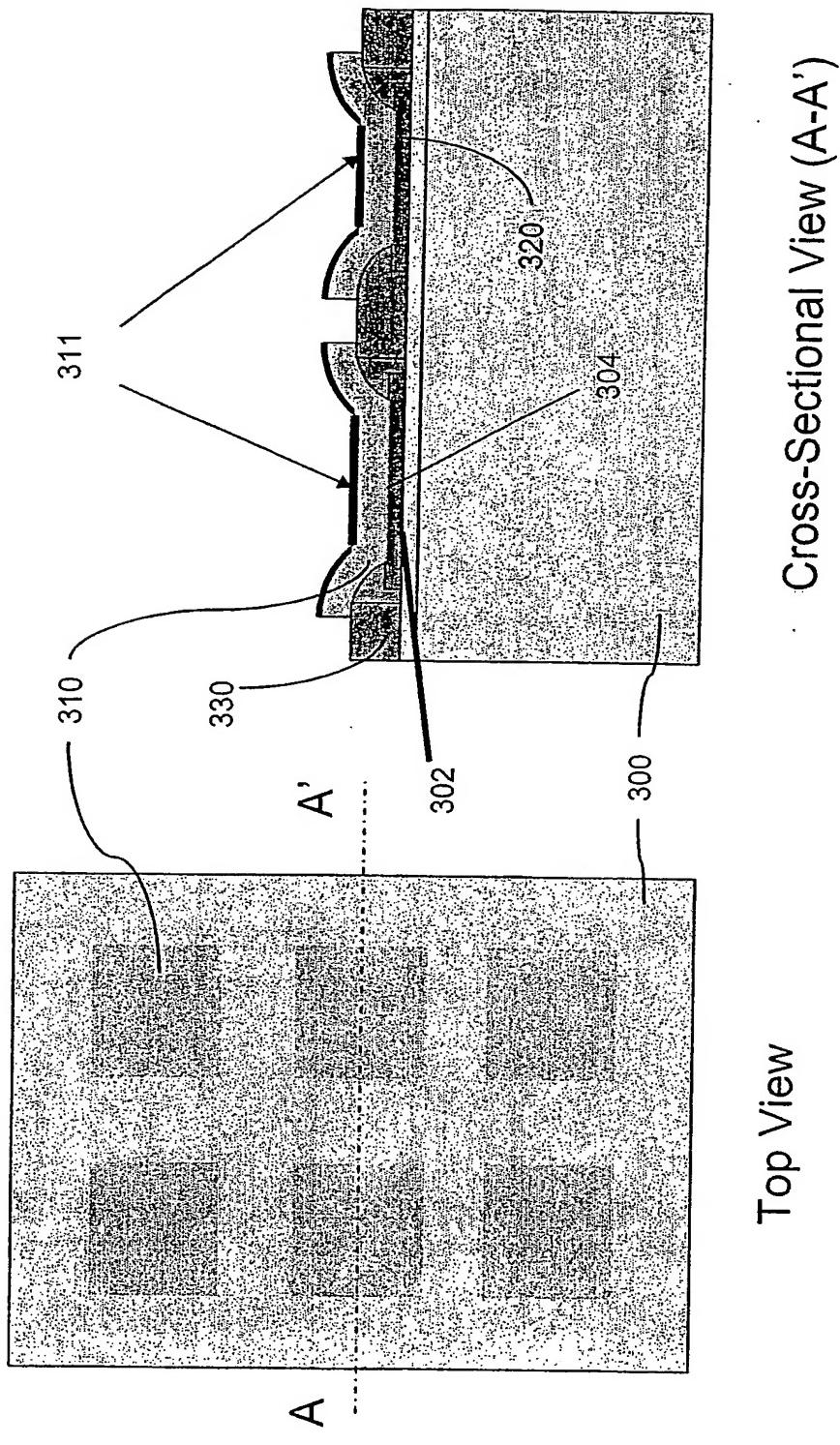


Figure 2. Typical Flip Chip Wafer Bumping Packages

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Top View

Cross-Sectional View (A-A')

Figure 3. Die with Solderable Metal Contacts for  
Direct Printed Circuit Board Mounting

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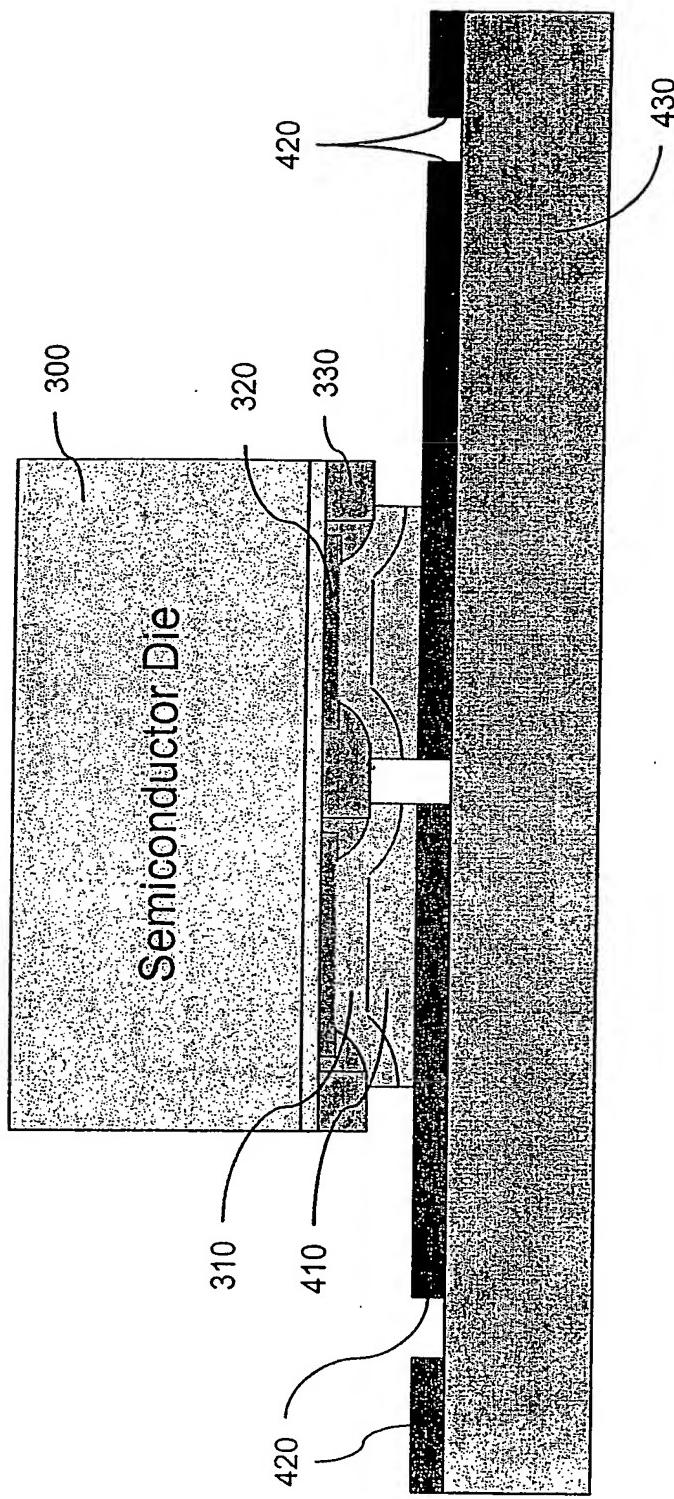


Figure 4. Illustration of Die with  
Solderable Electrical Contacts  
Mounted on Printed Circuit Board